

AMENDMENTS TO THE CLAIMS

Claims 1-46. (Canceled)

47. (New) A method for feeding electronic components to be mounted onto a board, comprising:

from a component feed tray in which electronic components are arranged, picking up one of said electronic components by using component holding and suction pressure of a component suction and holding member such that said one of said electronic components is sucked and held by said component suction and holding member,

wherein said component holding and suction pressure is not lower than a suction pressure capable of sucking and holding said one of said electronic components, and is lower than a suction pressure capable of sucking and holding said component feed tray.

48. (New) The method according to claim 47, wherein
picking up said one of said electronic components by using said component holding and suction pressure of said component suction and holding member, such that said one of said electronic components is sucked and held by said component suction and holding member, comprises

(i) bringing said component suction and holding member into contact with said one of said electronic components by lowering said component suction and holding member after aligning said component feed tray with said component suction and holding member,

(ii) creating suction pressure of said component suction and holding member such that the suction pressure reaches said component holding and suction pressure when said component suction and holding member starts ascending after being brought into contact with said one of said electronic components, and

(iii) sucking and holding said one of said electronic components with ascent

of said component suction and holding member.

49. (New) The method according to claim 48, further comprising:
determining a time for creating the suction pressure in consideration of an amount
of time necessary for the suction pressure to reach said component holding and suction
pressure from when the suction pressure is created by said component suction and holding
member.

50. (New) The method according to claim 48, wherein
creating the suction pressure of said component suction and holding member
comprises creating the suction pressure of said component suction and holding member
after said component suction and holding member is brought into contact with said one of
said electronic components.

51. (New) The method according to claim 48, further comprising:
determining a time for lowering said component suction and holding member
according to a size or a weight of said one of said electronic components so as to prevent
said one of said electronic components from leaping up from said component feed tray due
to said component suction and holding member being brought into contact with said one of said
electronic components.

52. (New) The method according to claim 47, wherein
said component holding and suction pressure is a suction pressure determined
according to a size or a weight of said one of said electronic components.